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(54) Title: A NEW ELECTRICAL CONDUCTOR FOR ATTACHING SILICON WAFERS IN PHOTOVOLTAIC MODULES

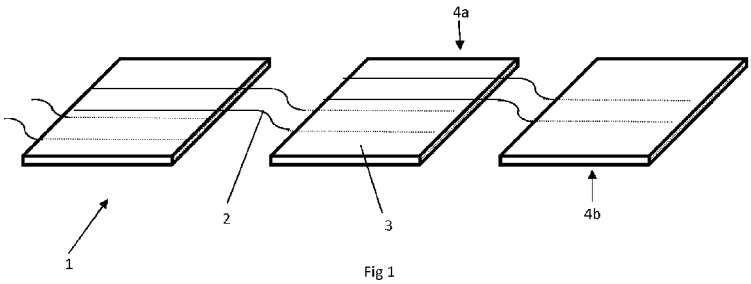


Fig 1

(57) Abstract: The invention relates to an electrical conductor (2) having a longitudinal axis (A) parallel to the rolling direction of a conductor wire, comprising copper material and an attachment surface (7) configured for attaching to a receiving surface of a silicon wafer (3) to establish an electrical connection. The copper material has a pu rity of at least 99.5% wherein the grains have a cubic texture comprising a set of cubic axes directed within an up to 20 degree angular range to the longitudinal axis (A), and whereby at least 65% of the grains have said cubic texture. The invention also relates to a process for manufacturing conductor (2) and photo-voltaic modules comprising said conductor (2), and silicon wafers.